



Inner Layer Bonding Technology

内层连结技术

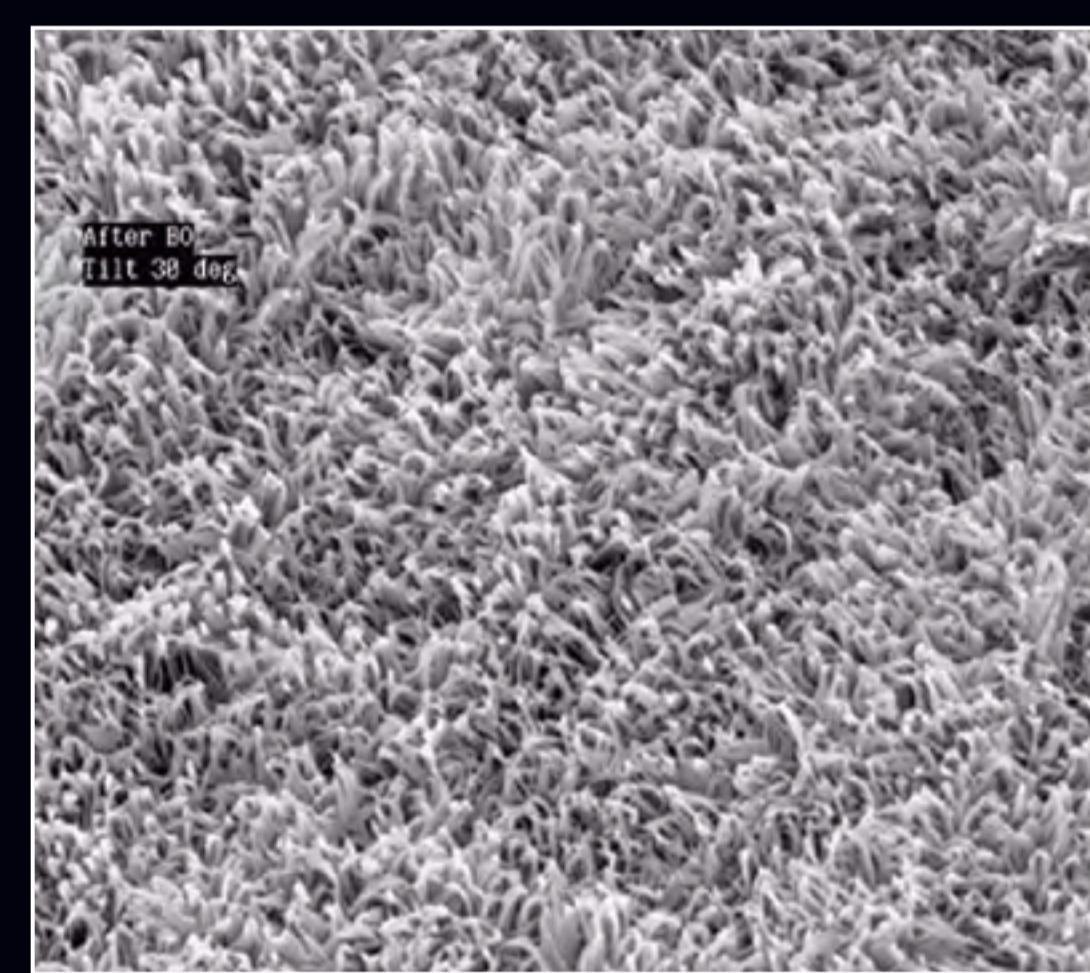
BLACK OXIDE – CIRCUPOSIT™ PB 484 OXIDE 黑化制程

For Traditional Applications 应用于传统压合制程

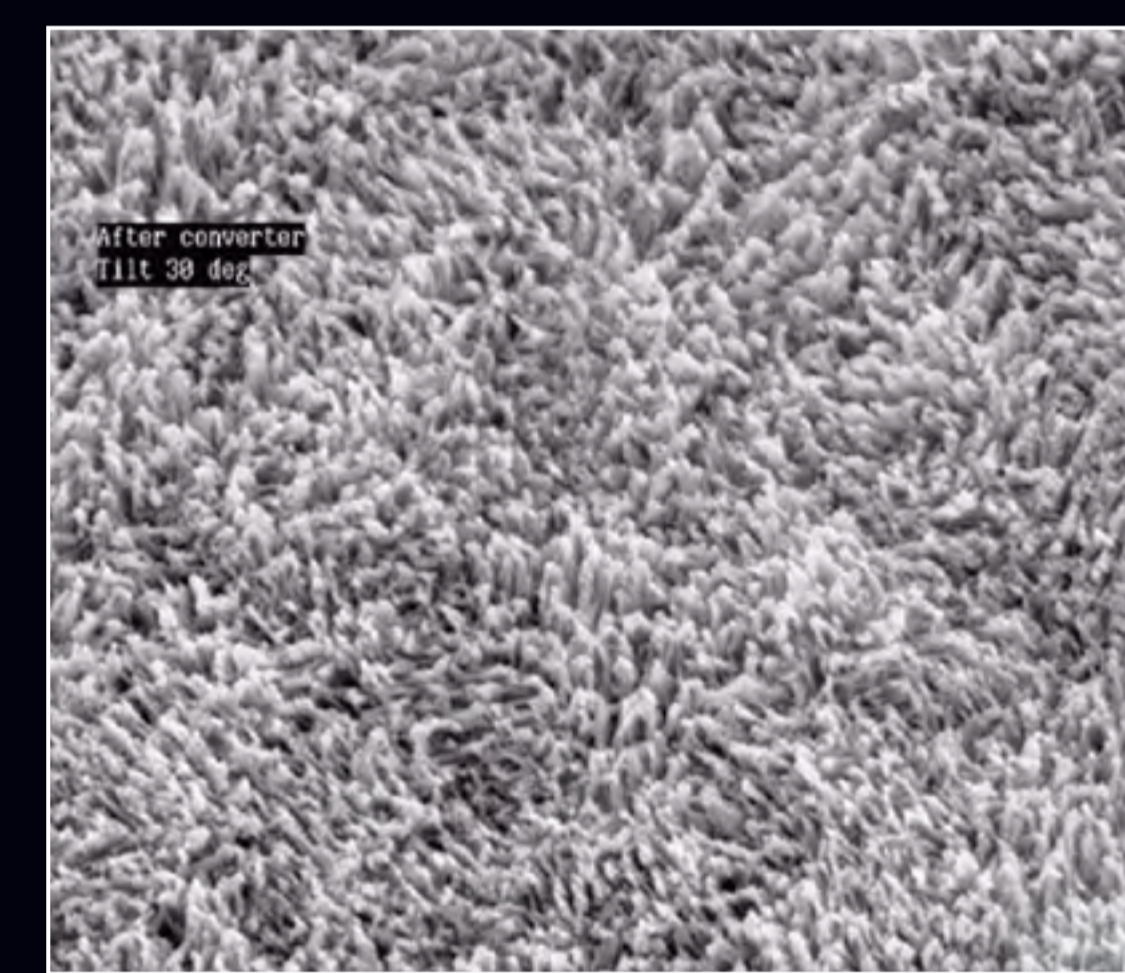
Advantages 优点

- Leading market share in Japan, USA, SEA and China markets
在日本, 美国, 东南亚及中国拥有高市占率
- Wide application range and compatible with all laminate types
宽广的操作范围并适用于各种类型的板材
- Best performance for high layer count applications
在多层板压合应用上, 有最佳的信赖度表现
- High peel strength on high Tg epoxy based laminates
应用在高Tg板材上有高抗剥离强度的表现
- Most stable process control and long bath life
药水操控稳定性高, 槽液寿命较长

SEM Comparison 电子显微镜下比较



Before Converter
还原前

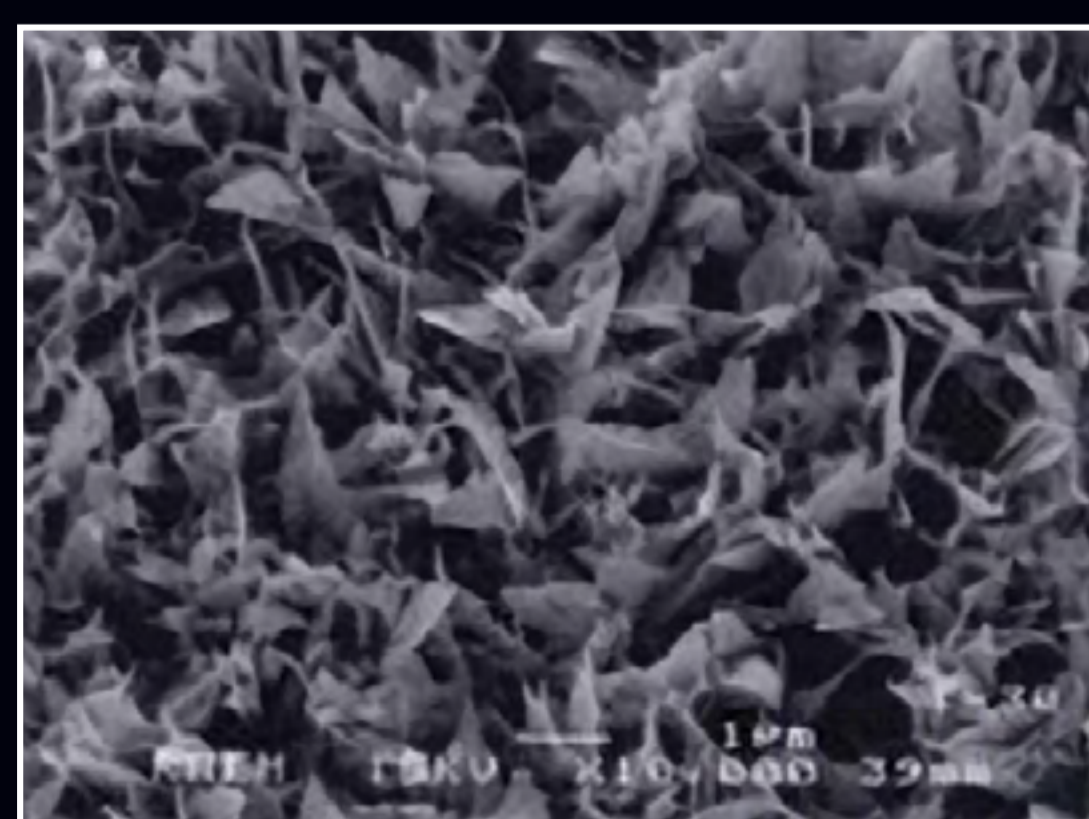


After Converter
还原后

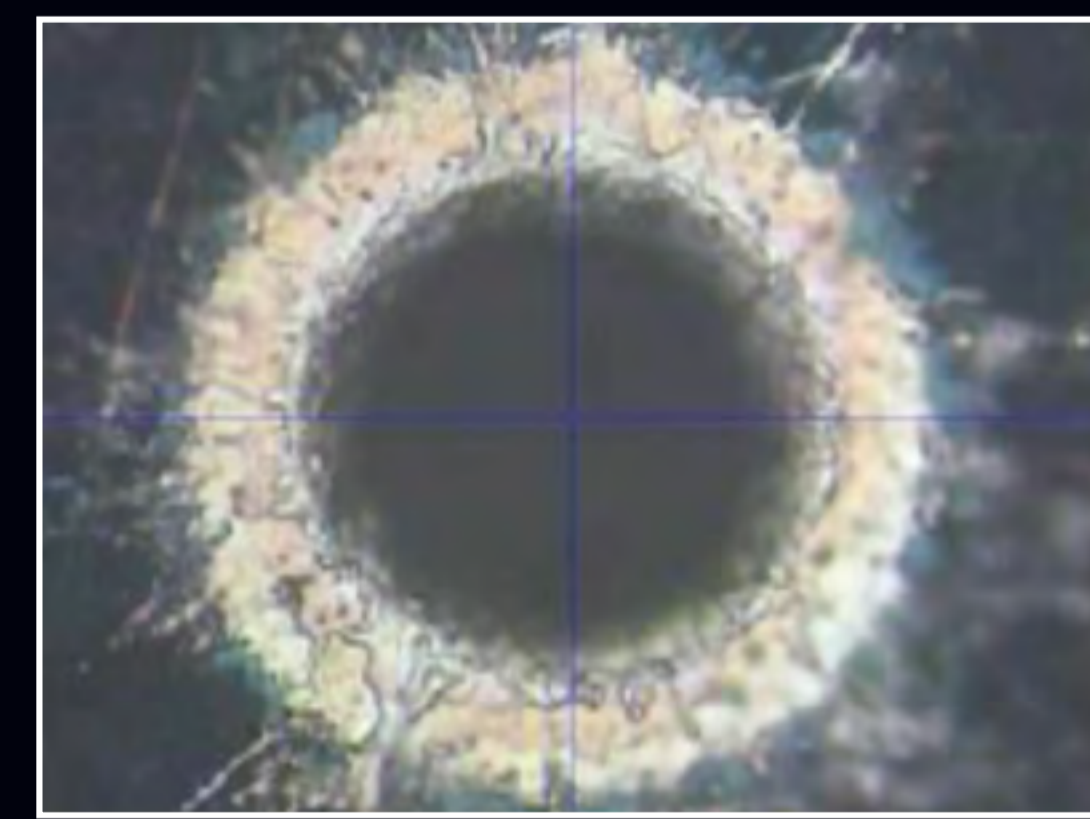
For Direct Laser Drilling Application in HDI 应用于HDI之直接电射钻孔制程

Advantages 优点

- Simplifies HDI process, leading to effective cost saving
简化HDI制程, 可有效降低成本
- Excellent microvia shape in hole formation
具有良好的盲孔孔真图度及盲孔孔型
- Reduces failures in hole registration
减少对位不良之现象
- Improves microvia yield rate, especially for smaller via diameters
改善盲孔的生产良率, 特别针对小孔径盲孔
- Most stable process control and long bath life
药水操控稳定性高, 槽液寿命较长



Compatible with DLD process
适用于直接电射钻孔的黑化结构



Excellent microvia shape in hole formation
具有良好的盲孔孔真图度及盲孔孔型

